







FUJI XPF-W SMT Pick And Place Machine for PCBs Up to 686mm x 508mm

Basic Information

Place of Origin: Japan
Brand Name: FUJI
Model Number: XPF-W
Minimum Order Quantity: 1 pcs

Price: USD+negotiable+pcsPackaging Details: 1800*2000*1650mm

Delivery Time: 1-7 daysPayment Terms: T/T

• Supply Ability: 1+pcs+per days



Product Specification

Model: FUJI XPF-W

PCB Size:
 L50mm X W50mm To L686mm X W508mm

PCB Thickness: 0.4–6.5mmPCB Loading Time: 3.5 Sec

External Dimension: L1500 X W1762.5 X H1422.5mm
 Weight: Approx. 1860kg without MFU Mounted

• Highlight: Multi Purpose SMT Pick And Place Machines,

PCB SMT Pick And Place Machines, SMT PCB Pick And Place Machine



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FUJI XPF-W Multi Purpose SMT Pick And Place Machines For PCB Production

The FUJI XPF-L/W High-speed Multi-Purpose Mounter is a state-of-the-art machine designed to enhance productivity and flexibility in electronics manufacturing. It excels in high-speed component placement while being adaptable for a wide range of surface-mount technology (SMT) applications.

Key Functions

High-Speed Component Placement: Equipped with high-speed heads for rapid and precise placement of components from small chips to large ICs, optimizing throughput while maintaining accuracy.

Versatility in Handling Different Components: Capable of processing 0201 microchips, odd-shaped components, and larger devices like connectors, making it flexible for various SMT jobs.

On-the-Fly Component Centering: High-precision vision system ensures accurate placement at high speeds, reducing manual intervention and minimizing errors.

Multi-Function Head: Single head can switch between different tasks, eliminating need for separate machines and improving productivity.

Automatic Feeder Exchange: Supports continuous production with minimal stoppages through automatic feeder cart swapping.

Flexible PCB Handling: Accommodates wide range of PCB sizes from small boards to complex panels with adjustable conveyor system.

Nozzle Changer System: Automatic nozzle storage and exchange capability enhances ability to place diverse component types without manual intervention.

Advanced Software Integration: Seamless integration with FUJI's proprietary software for real-time tracking, production analysis, and remote monitoring.

Non-Stop Operation: Dynamic load balancing distributes work evenly across multiple heads for consistent production and extended machine life.

Hybrid Placement Capability: Combines chip shooting and fine-pitch placement in one unit for diverse SMT component handling.

Key Features

Compact Design: Space-efficient footprint for easy integration into existing production lines.

High Precision and Accuracy: Advanced motion control systems ensure precise placement of tiny components on high-density boards.

Scalable Production: Ideal for high-mix/low-volume environments with fast setup times and automatic changeover functions.

Wide Component Size Range: Handles components from 0201 microchips to large ICs and connectors.

User-Friendly Interface: Intuitive controls simplify setup, operation, and maintenance.

Energy-Efficient: Reduces power consumption without compromising performance.

Error Detection: Built-in systems identify and correct misplacements to minimize rework.

Modular Design: Easy maintenance and upgrades with quick component replacement.

Wide Operating Range: Consistent performance in challenging production environments.

Industry Compliance: Meets latest standards for SMT equipment in quality control and safety.



Model	FUJI XPF-W	
PCB size	L50mm x W50mm to L686mm x W508mm	
PCB Thickness	0.4-6.5mm	
Auto-Tool	Revover Auto-Tool	Single Nozzle
Number of Auto-Tool held in auto- tool station	3	8
Supported Parts	0402 (01005) to 20x20mm Maximum, height: 3.0 mm	1005(0402) to 45×150 (45×45)mm Maxmum, height: 25.4 mm
Machine Test	0.144 sec/component, 25000cph	0.40 sec/component, 9000cph
Small Chip Parts Placing Accuracy	+/-0.050mm CPK ≥ 1.00	+/-0.040mm CPK ≥ 1.00
	+/-0.066mm CPK ≥ 1.33	+/-0.053mm CPK ≥ 1.33
QFP Placing Accuracy	+/-0.040mm CPK ≥ 1.00	+/-0.030mm CPK ≥ 1.00
	+/-0.053mm CPK ≥ 1.33	+/-0.040mm CPK ≥ 1.33
PCB Loading Time	3.5 sec	
External dimension	L1500 x W1762.5 x H1422.5mm	
	(Transport height: 900mm; not include the Signal tower)	
Weight	Approx. 1860kg (without MFU mounted)	

The FUJI XPF-L/W High-speed Multi-Purpose Mounter is a highly advanced, flexible, and reliable solution for optimizing SMT processes, reducing downtime, and improving productivity across various production environments.

FUJI XPF-W: Versatile SMT Machine for High-Mix, Low-Volume PCB Production | GSSMT, FUJI XPF-L/W mounter, FUJI high-speed mounter, FUJI XPF-L/W SMT machine, FUJI XPF-L/W placement accuracy, FUJI multi-purpose mounter, FUJI XPF-L/W component feeder, FUJI SMT equipment XPF-L/W, FUJI XPF-L/W placement accuracy, FUJI multi-purpose mounter, FUJI XPF-L/W component feeder, FUJI SMT equipment XPF-L/W, FUJI XPF-L/W component feeder, L/W PCB assembly, FUJI XPF-L/W features, FUJI XPF-L/W specifications, FUJI XPF-L/W performance review, FUJI XPF-L/W maintenance, FUJI XPF-L/W vs other mounters, FUJI XPF-L/W high-speed placement, FUJI XPF-L/W vision system





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